2SC5846G

Silicon NPN epitaxial planar type

For general amplification

■ Features

- High forward current transfer ratio h_{FE}
- SSS-mini type package, allowing downsizing and thinning of the equipment and automatic insertion through the tape packing

■ Package

- Code
  SSSMini3-F2
- Marking Symbol: 7K
- Pin Name
  1. Base
  2. Emitter
  3. Collector

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	60	V
Collector-emitter voltage (Base open)	V_{CEO}	50	V
Emitter-base voltage (Collector open)	V_{EBO}	7	V
Collector current	I_C	100	mA
Peak collector current	I_{CP}	200	mA
Collector power dissipation	P_C	100	mW
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	−55 to +125	°C

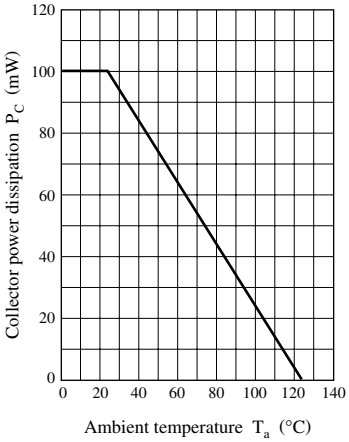
■ Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_C = 10\ \mu A$, $I_E = 0$	60			V
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = 2$ mA, $I_B = 0$	50			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 10\ \mu A$, $I_C = 0$	7			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 20$ V, $I_E = 0$			0.1	μA
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = 10$ V, $I_B = 0$			100	μA
Forward current transfer ratio	h_{FE}	$V_{CE} = 10$ V, $I_C = 2$ mA	180		390	—
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = 100$ mA, $I_B = 10$ mA		0.1	0.3	V
Collector output capacitance (Common base, input open circuited)	C_{ob}	$V_{CB} = 10$ V, $I_E = 0$, f = 1 MHz		2.2		pF
Transition frequency	f_T	$V_{CB} = 10$ V, $I_E = -2$ mA, f = 200 MHz		100		MHz

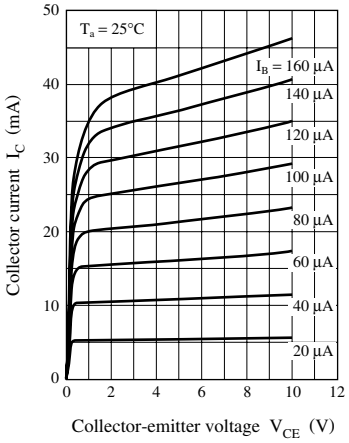
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

Maintenance/Discontinued
This product includes following four Product lifecycle stage.
Maintenance type
Discontinued type
Discontinued typed
Please visit following URL about latest information.
http://panasonic.net/sys/en

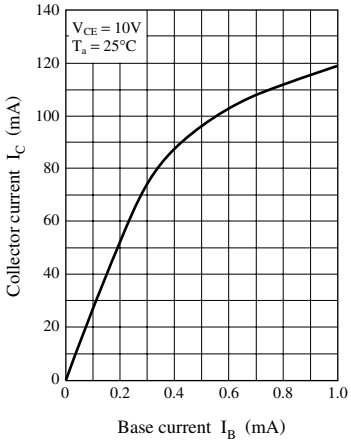
P_C — T_a



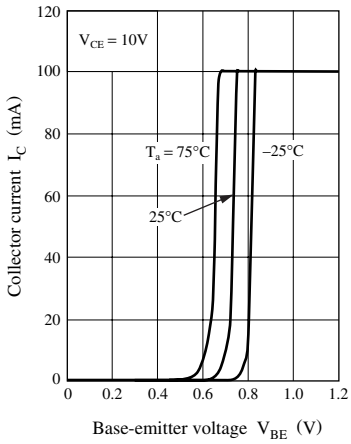
I_C — V_{CE}



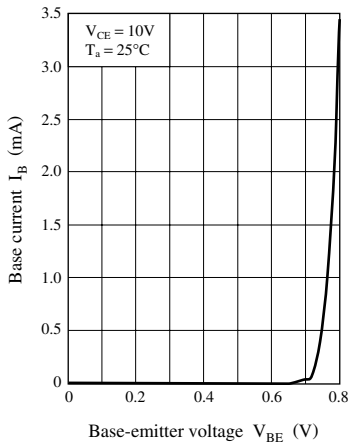
I_C — I_B



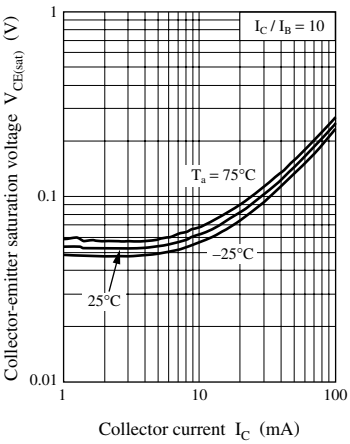
I_C — V_{BE}



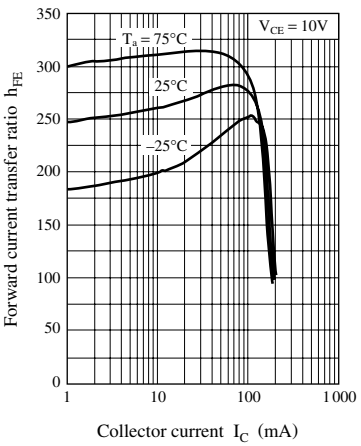
I_B — V_{BE}



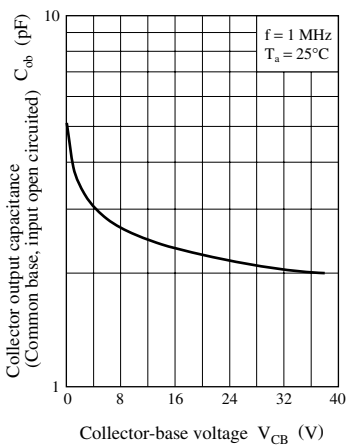
$V_{CE(sat)}$ — I_C



h_{FE} — I_C

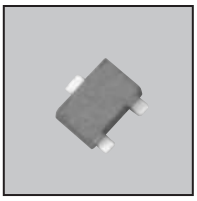


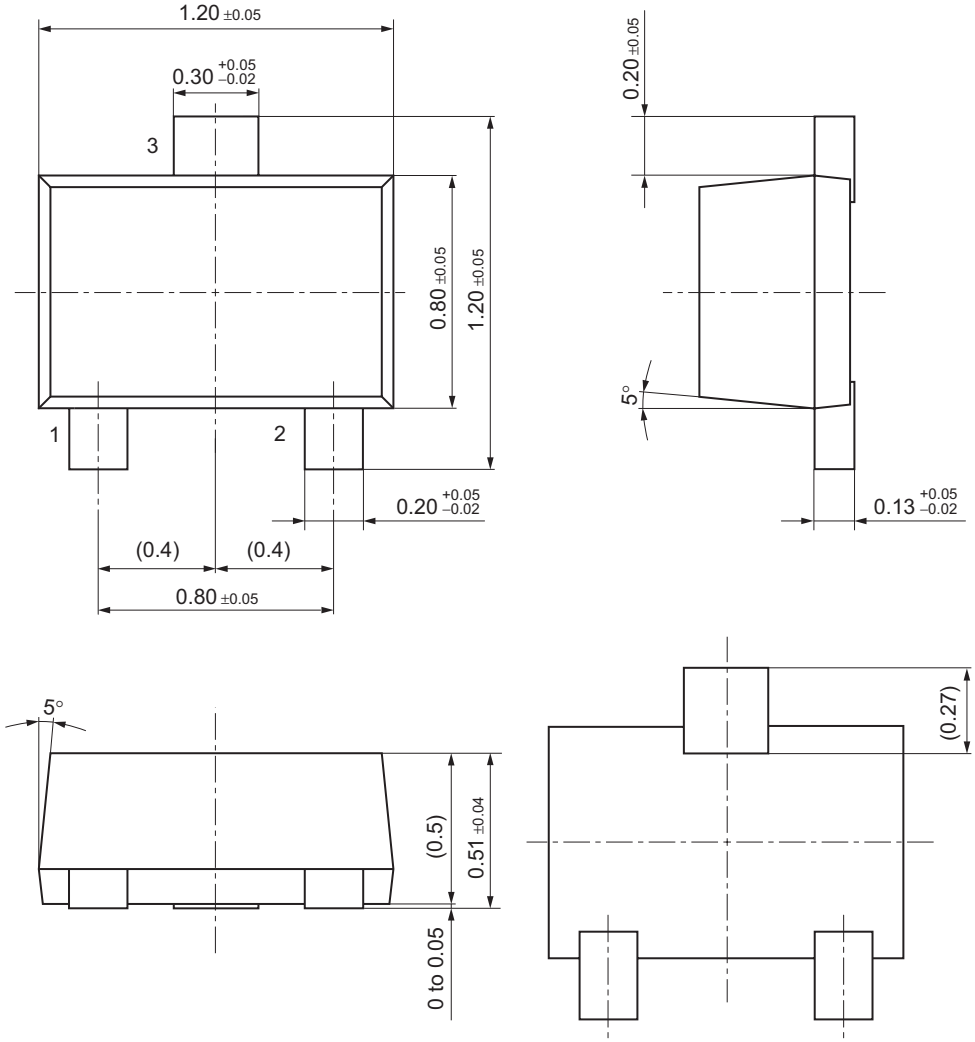
C_{ob} — V_{CB}



SSSMini3-F2

Unit: mm





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